

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1-9. (Canceled)

10. (Currently Amended) ~~The A~~ photosensitive resin composition ~~as set forth in claim 2, wherein the (meth)acryls, comprising a base resin component (A) and a~~ (meth)acrylic compound (B) as essential components, wherein

the base resin component (A) is a polyimide resin (A-1) having at least either a hydroxyl group or a carboxyl group in its structure or a polyamide resin (A-2) having at least either a hydroxyl group, and

the (meth)acrylic compound (B) is an epoxy (meth)acrylate having at least two hydroxyl groups in its molecule.

11- 20 (Canceled).

21. (Currently amended) ~~The A~~ photosensitive resin composition ~~as set forth in claim 12, wherein the (meth)acryls, comprising a base resin component (A) and a~~ (meth)acrylic compound (B) as essential components, wherein

the base resin component (A) is a polyimide resin (A-1) having at least either a hydroxyl group or a carboxyl group in its structure and the polyimide resin (A-1) is a photosensitive polyimide resin (A-1-2) obtained by reacting a compound having a carbon-carbon double bond with a polyimide resin having a hydroxyl group in its structure, and

the (meth)acrylic compound (B) is an epoxy (meth)acrylate having at least two hydroxyl groups in its molecule, and

the photosensitive resin composition further includes, as an accessory component (C), at least one kind (C-1) selected from a photoreaction initiator, a sensitizer, and a photopolymerization assistant.

22 – 49. (Cancelled).